



Advance Product Change Notification

201811044A

Issue Date: 20-Dec-2018

Here's your personalized quality information concerning products Digi-Key purchased from NXP.

For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.



QUALITY

Change Category

Wafer Fab Process

Wafer Fab Materials

Wafer Fab Location

Firmware

Assembly Process

Assembly Materials

Assembly Location

Other

Product Marking

Mechanical Specification

Packing/Shipping/Labeling Equipment

Test Location

Test Process

Test Equipment

Design

Errata

Electrical spec./Test coverage

**PRE ALERT: SPC5777C,
SPC5775B/E Burn-In/ Assembly
and Final Test Site Expansions**

Description of Change

NXP Semiconductors announces the following site expansions for the SPC5777C/ B/ E, Mask Set N45H products associated with this notification:

1. Assembly site expansion from the current NXP-ATTJ, Tianjin, China assembly facility to the NXP-ATKL, Kuala Lumpur, Malaysia assembly facility.
2. Burn-in site expansion from the current KESM (Kuala Lumpur), Kuala Lumpur, Malaysia Burn-in site to the KESM (Tianjin), Tianjin, China Burn-in site.
3. Final test site expansion from the current NXP-ATKL, Kuala Lumpur, Malaysia Final Test site to the NXP-ATTJ, Tianjin, China Final Test site.

For the assembly site expansion, there is no change to the package bill of material (BOM) between the two assembly sites.

Expected qualification of associated sites is April 2019. An update to this notification with qualification results will be issued at that time.

Supplemental information on Prototype Part numbers for sample orders, Key Dates and the part number Nomenclature Decoder for the assembly site expansion are attached.

The above changes coincides with DeQuMa ID: SEM-PA-18 and SEM-TF-01.

Reason for Change

Site expansion qualification is required for manufacturing flexibility and customer supply assurance.

Identification of Affected Products

The assembly site, among other information, is reflected in the package trace code.

Please refer to the marking explanation in the supplemental information file attached.

Product Availability

Sample Information

Samples are available from 25-Jan-2019

Refer to supplementary information file attached for sample part numbers.

Production

Planned first shipment 23-Jul-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

Depletion of inventory not applicable for site expansions.

Timing and Logistics

The Self Qualification Report will be ready on 23-Apr-2019.

The Final PCN is planned to be issued on: 23-Apr-2019.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 19-Jan-2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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NXP Semiconductors

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Affected Part Numbers

SPC5777CK2MMO3

SPC5777CCK3MME3

SPC5777CK2MME3

SPC5777CK3MMO3

SPC5775BDK3MME2

SPC5777CK3MME3

SPC5775EDK3MME3